



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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# SPECIFICATION

(Reference sheet)

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

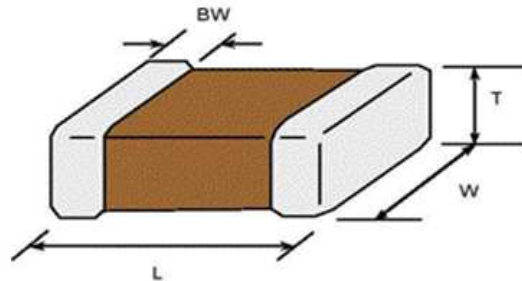
- Samsung P/N : **CL10C100JB8NNNC**
- Description : **CAP, 10pF, 50V, ± 5%, COG, 0603**

## A. Samsung Part Number

**CL**   **10**   **C**   **100**   **J**   **B**   **8**   **N**   **N**   **N**   **C**  
 ①   ②   ③   ④   ⑤   ⑥   ⑦   ⑧   ⑨   ⑩   ⑪

① <b>Series</b>	Samsung Multi-layer Ceramic Capacitor		
② <b>Size</b>	0603 (inch code)	L: 1.60 ± 0.10 mm	W: 0.80 ± 0.10 mm
③ <b>Dielectric</b>	COG	⑧ <b>Inner electrode Termination</b>	Ni
④ <b>Capacitance</b>	10 pF	⑨ <b>Plating</b>	Cu
⑤ <b>Capacitance tolerance</b>	± 5 %	⑩ <b>Product</b>	Sn 100% (Pb Free)
⑥ <b>Rated Voltage</b>	50 V	⑪ <b>Special</b>	Normal
⑦ <b>Thickness</b>	0.80 ± 0.10 mm		Reserved for future use
			Cardboard Type, 7" reel

## B. Structure and dimension



Samsung P/N (Lead Free)	Dimension(mm)			
	L	W	T	BW
CL10C100JB8NNNC	1.60 ± 0.10	0.80 ± 0.10	0.80 ± 0.10	0.30 ± 0.20

### C. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1MHz±10%      0.5~5Vrms
Q	600 min	
Insulation Resistance	10,000Mohm or 500Mohm× $\mu$ F Whichever is smaller	Rated Voltage      60~120 sec.
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	300% of the rated voltage
Temperature Characteristics	C0G (From -55°C to 125°C, Capacitance change should be within ±30PPM/°C)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g×F, for 10±1 sec.
Bending Strength	Capacitance change : within ±5% or ±0.5pF whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5°C, 10±1sec.
Vibration Test	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within ±7.5% or ±0.75pF whichever is larger Q :      133.33 min IR :      500Mohm or 25Mohm × $\mu$ F Whichever is smaller	With rated voltage 40±2°C, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within ±3% or ±0.3pF whichever is larger Q :      300 min IR :      1,000Mohm or 50Mohm × $\mu$ F Whichever is smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	1 cycle condition Min. operating temperature      → 25°C → Max. operating temperature → 25°C  5 cycle test

※ The reliability test condition can be replaced by the corresponding accelerated test condition.

### D. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )

 Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

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We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

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- ② Automotive or Transportation equipment (vehicles, trains, ships, etc)
- ③ Medical equipment
- ④ Military equipment
- ⑤ Disaster prevention/crime prevention equipment
- ⑥ Any other applications with the same as or similar complexity or reliability to the applications set forth above.